

a lower surface of the multilayer body **110** and surfaces of the multilayer body **110** perpendicular to a stacking surface thereof is formed by stacking the insulating sheets on which the internal coil patterns are formed.

[0070] A via may be formed at a predetermined position in each of the insulating layers on which the internal coil patterns are printed, and the internal coil patterns formed on each of the insulating layers may be electrically connected to each other through the via, thereby forming a single coil.

[0071] The first and second lead portions **121'** and **122'** of the internal coil parts **121** and **122** formed as the single coil are exposed at the lower surface of the multilayer body **110** and the surfaces of the multilayer body **110** perpendicular to the stacking surface of the multilayer body **110**. The internal coil parts **121** and **122** may be formed in a plane perpendicular to a substrate mounting surface of the multilayer body **110**.

[0072] Thereafter, in operation **S250**, first and second external electrodes **131** and **132** connected to the first and second lead portions **121'** and **122'** of the internal coil parts **121** and **122**, respectively, may be formed on the lower surface of the multilayer body **110** and the surfaces of the multilayer body **110** perpendicular to the stacking surface of the multilayer body **110**. The first and second external electrodes **131** and **132** may be formed using a conductive paste containing a metal having excellent electric conductivity. The conductive paste may contain one of nickel (Ni) and tin (Sn), an alloy thereof, or the like.

TABLE 1

Classification	L [nH]	Q	Rs
Comparative Example	0.440	30.764	0.216
Example Embodiment	0.443	32.634	0.205

[0073] Referring to Table 1 above, it can be appreciated that in a case of a multilayer electronic component according to the disclosed embodiments, inductance (L) and a Q value were improved, and equivalent series resistance (Rs) was decreased as compared to the Comparative Example according to the related art. Specifically, in the Example Embodiment of Table 1, inductance (L) was increased by 0.7% and the Q value was improved by 6.1% as compared to the Comparative Example.

[0074] In addition, it can be appreciated that in the Example Embodiment, equivalent series resistance (Rs) was decreased by 5.1% as compared to the Comparative Example.

[0075] A description of other features overlapping those of the multilayer electronic component **100** described above will be omitted in order to avoid repetitive disclosure.

[0076] As set forth above, according to example embodiments disclosed herein, equivalent series resistance (Rs) may be decreased by coating a material having a low specific resistance value on outermost internal coil parts on which magnetic flux and current are concentrated due to a skin effect and a parasitic effect. Therefore, a multilayer electronic component having an improved Q factor may be provided.

[0077] While this disclosure includes specific examples, it will be apparent to one of ordinary skill in the art that various changes in form and details may be made in these examples without departing from the spirit and scope of the claims and their equivalents. The examples described herein are to be

considered in a descriptive sense only, and not for purposes of limitation. Descriptions of features or aspects in each example are to be considered as being applicable to similar features or aspects in other examples. Suitable results may be achieved if the described techniques are performed in a different order, and/or if components in a described system, architecture, device, or circuit are combined in a different manner, and/or replaced or supplemented by other components or their equivalents. Therefore, the scope of the disclosure is defined not by the detailed description, but by the claims and their equivalents, and all variations within the scope of the claims and their equivalents are to be construed as being included in the disclosure.

What is claimed is:

1. A multilayer electronic component, comprising:
 - a multilayer body comprising stacked insulating layers and internal coil parts disposed on the insulating layers;
 - external electrodes disposed on an outer portion of the multilayer body and connected to the internal coil parts; and
 - a material layer disposed on an outermost internal coil part among the internal coil parts and having a specific resistance that is lower than a specific resistance of the internal coil parts.
2. The multilayer electronic component of claim 1, wherein the material layer comprises silver (Ag).
3. The multilayer electronic component of claim 1, wherein the internal coil parts comprise externally exposed first and second lead portions.
4. The multilayer electronic component of claim 2, wherein the first and second lead portions have an L shape in a cross section of the multilayer body in a length-thickness plane.
5. The multilayer electronic component of claim 1, wherein the multilayer body further comprises an externally exposed a dummy lead part disposed on the insulating layers.
6. The multilayer electronic component of claim 1, wherein the internal coil parts are disposed in planes perpendicular to a substrate mounting surface of the multilayer body.
7. The multilayer electronic component of claim 1, wherein the external electrodes are disposed on end surfaces of the multilayer body or a bottom surface of the multilayer body.
8. A method of manufacturing a multilayer electronic component, the method comprising:
 - preparing insulating sheets;
 - forming internal coil patterns on the insulating sheets;
 - applying a material layer having a specific resistance lower than a specific resistance of the internal coil patterns onto an outermost internal coil pattern among the internal coil patterns;
 - stacking the insulating sheets to form a multilayer body including internal coil parts formed by the internal coil patterns; and
 - forming external electrodes connected to the internal coil parts on an outer portion of the multilayer body.
9. The method of claim 8, wherein the material layer comprises silver (Ag).
10. The method of claim 8, wherein the internal coil parts comprise externally exposed first and second lead portions.